

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 260 C/10 seconds at terminals



DO-214AC (SMA)

Mechanical Data

- Case: Transfer molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Lead :Solder plated, solderable per MIL-STD-750 method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.002 ounce, 0.064 gram

Maximum Ratings and Electrical Characteristics

- Ratings at 25°C ambient temperature unless otherwise specified
- Single phase, half wave, 60Hz, resistive or inductive load
- For capacitive load derate current by 20%

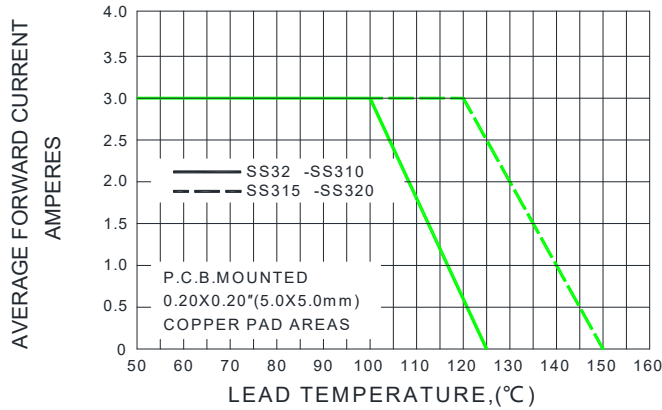
TYPE NUMBER		SYMBOL S	SS 32	SS 34	SS 35	SS 36	SS 38	SS 310	SS 315	SS 320	UNIT
Maximum Repetitive Peak Reverse Voltage		V _{RRM}	20	40	50	60	80	100	150	200	Volts
Maximum RMS Voltage		V _{RMS}	14	28	35	42	56	70	105	140	Volts
Maximum DC Blocking Voltage		V _{DC}	20	40	50	60	80	100	150	200	Volts
Maximum Average Forward Rectified Current at T _L see figure 1 T _L =100°C		I _(AV)	3.0								Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)		I _{FSM}	80								Amps
Maximum Instantaneous Forward Voltage @ 3.0A(Note1)		V _F	0.55		0.70		0.85		0.90		Volts
Maximum DC Reverse Current at rated DC Blocking Voltage per element	T _A = 25°C	I _R	0.1						0.01		mA
	T _A = 100°C		20.0				10.0		2.0		
Typical Thermal Resistance (Note 2)		R _{θJA}	55								°C/W
		R _{θJL}	25								
Diode junction capacitance (Note 3)		C _J	300		200						pF
Operating Junction Temperature		T _J	(-55 to +150)						(-65 to +175)		°C
Storage Temperature Range		T _{STG}	(-55 to +150)								°C

Notes:

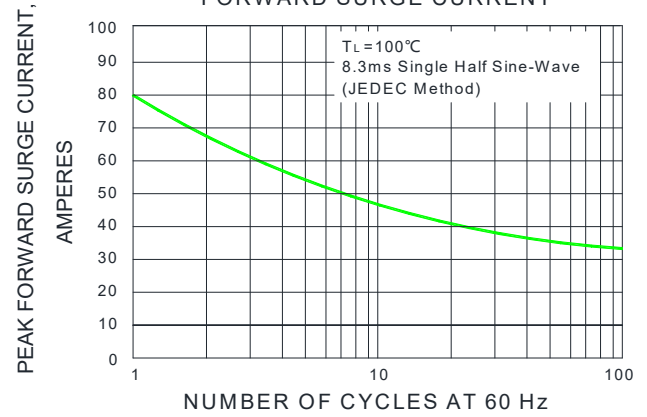
1. Pulse test: 300μs pulse width, 1% duty cycle.
2. Unit mounted on P.C.B. with 0.20"×0.20" (5.00mm×5.00mm) copper pads.
3. f=1MHz and applied 4V DC reverse voltage.

Ratings and Characteristic Curves (TA=25°C unless otherwise noted)

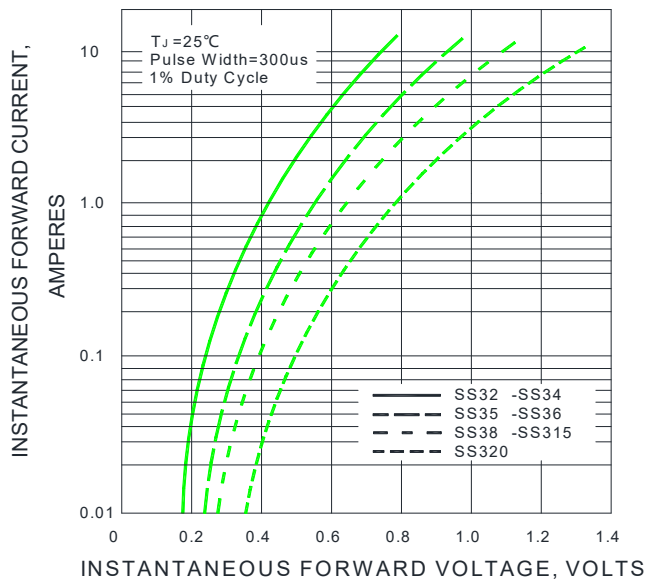
F1G.1-FORWARD CURRENT DERATING CURVE



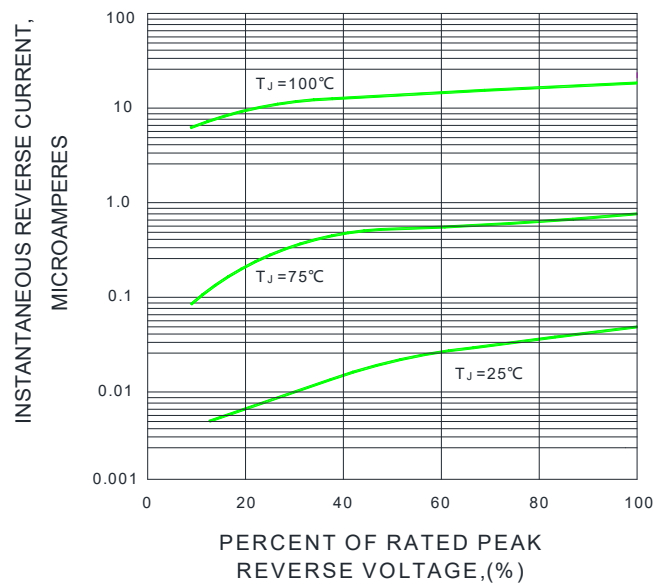
F1G.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



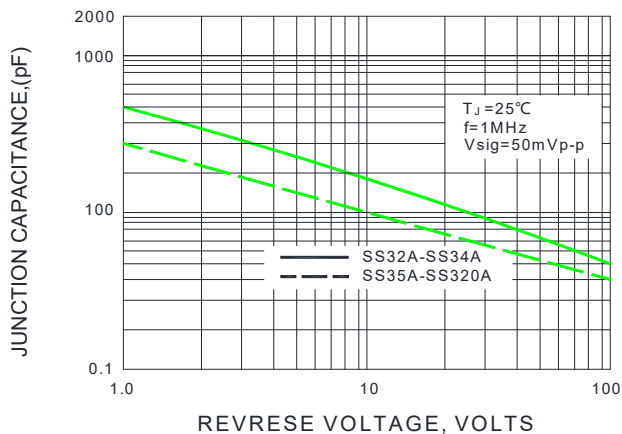
F1G.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



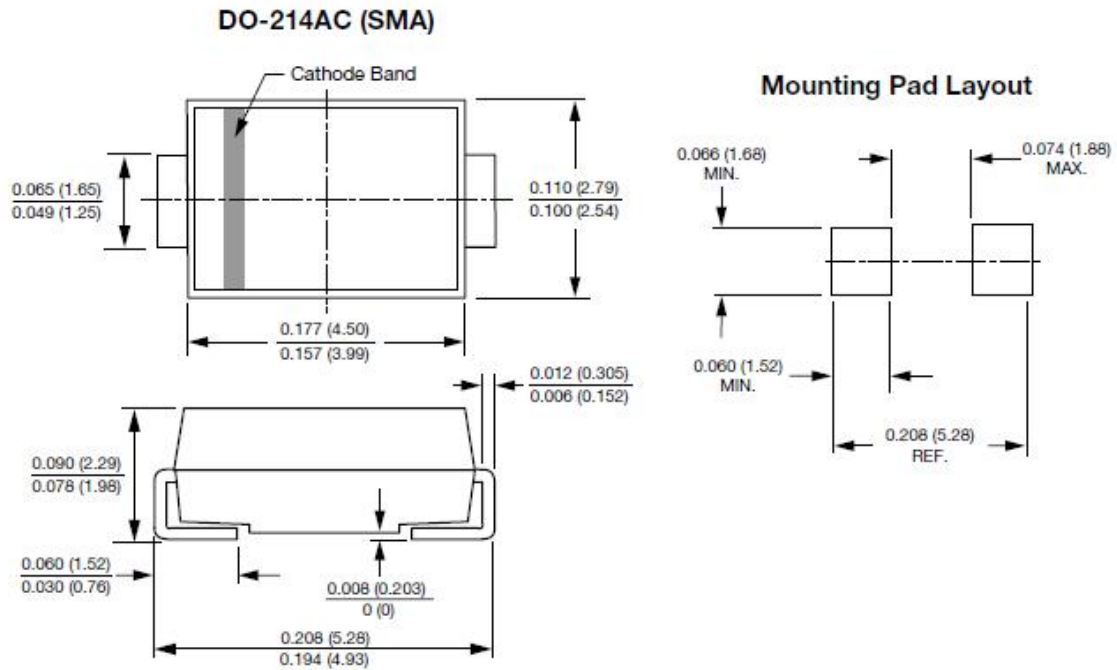
F1G.4-TYPICAL REVERSE CHARACTERISTICS



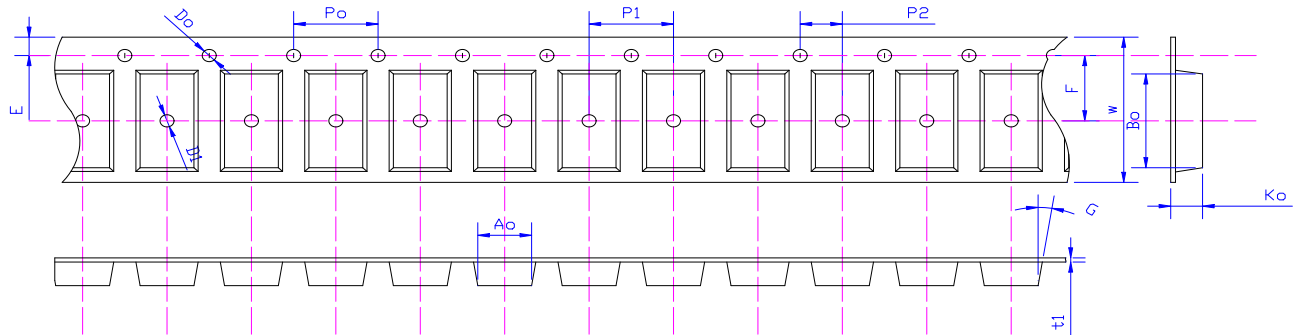
F1G.5-TYPICAL JUNCTION CAPACITANCE



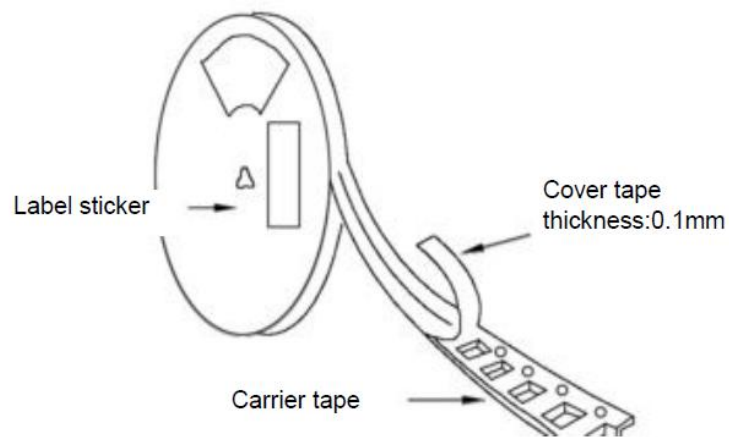
Package Outline Dimensions in inches (millimeters)



Package Reel Information



Specifications	Ao	Bo	Ko	Po	W	t1
SMA	2.55±0.10	5.10±0.10	2.36±0.10	4.00±0.1	12.0±0.05	0.23±0.02



DEVICE TYPE	Tape Width	13"Reel			07"Reel			
		Q'TY/REEL(pcs)	BOX/CARTON	Q'TY/CARTON(pcs)	Q'TY/REEL(pcs)	REEL/BOX	BOX/CARTON	Q'TY/CARTON(pcs)
SMA	12mm	5000	8	80000	1500	2	16	48000

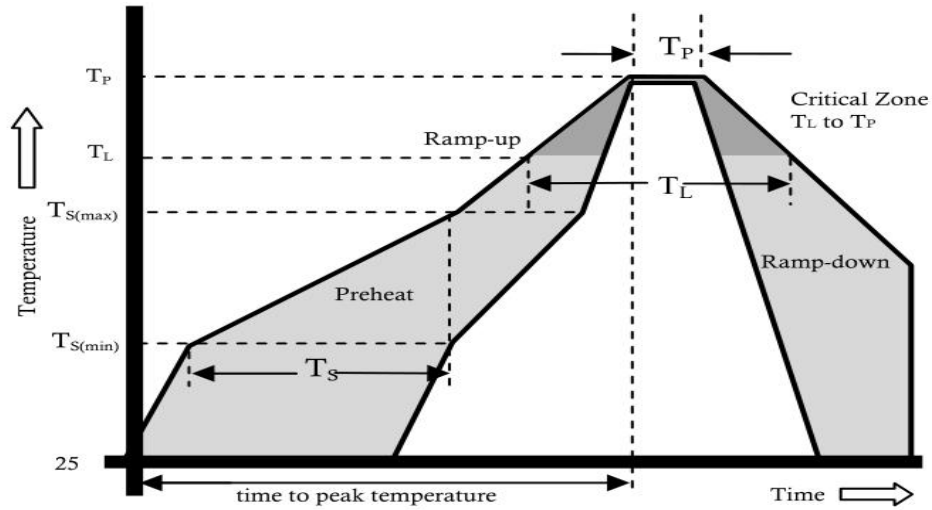


HAICHUANG SEMI

SS32 THRU SS320

VOLTAGE RANGE 20 to 200 Volts
CURRENT 3.0 Ampere

Reflow Profile



Reflow Condition		Pb-Free Assembly
Pre Heat	Temperature Min.	+150°C
	Temperature Max.	+200°C
	Time(Min to Max)	60-180 secs.
Average ramp up rate(Liquidus Temp(T_L) to peak)		3°C/sec. Max.
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	Temperature (T_L)(Liquidus)	+217°C
	Temperature (T_L)	60-150 secs.
Peak Temp (T_P)		+(260+0/-5)°C
Time within 5°C of actual Peak Temp (T_P)		25 secs.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to peak Temp (T_P)		8 min. Max.
Do not exceed		+260°C